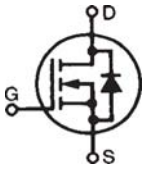
IXYS

High Voltage Power MOSFET

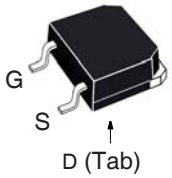
IXTT02N450HV
IXTH02N450HV

V_{DSS} = 4500V
I_{D25} = 200mA
$R_{DS(on)}$ ≤ 625Ω

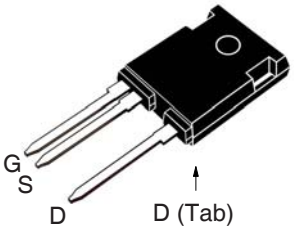
N-Channel Enhancement Mode



TO-268HV (IXTT)



TO-247HV (IXTH)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	4500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	4500	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	200	mA
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	600	mA
P_D	T_C = 25°C	113	W
T_J		- 55 ... +150	°C
T_{JM}		150	°C
T_{stg}		- 55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_d	Mounting Torque	1.13/10	Nm/lb.in
Weight	TO-268HV	4	g
	TO-247HV	6	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	4.0		6.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	V_{DS} = 3.6kV, V_{GS} = 0V			5	μA
	V_{DS} = 4.5kV			10	μA
	V_{DS} = 3.6kV T_J = 125°C		15		μA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 10mA, Note 1			625	Ω

Features

- High Blocking Voltage
- High Voltage Packages

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- High Voltage Power Supplies
- Capacitor Discharge Applications
- Pulse Circuits
- Laser and X-Ray Generation Systems

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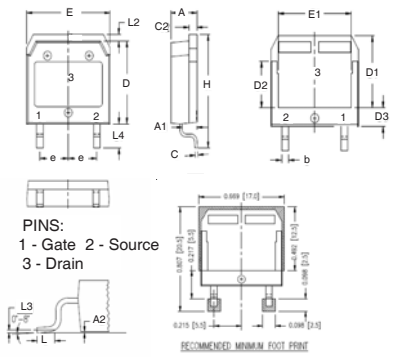
Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 50V, I_D = 50mA, Note 1	90	150		mS
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		246		pF
C_{oss}			19		pF
C_{rss}			5.8		pF
R_{Gi}	Gate Input Resistance		76		Ω
$t_{d(on)}$	**Resistive Switching Times**		17		ns
t_r	V_{GS} = 10V, V_{DS} = 500V, I_D = 0.5 • I_{D25}		48		ns
$t_{d(off)}$	R_G = 10Ω (External)		28		ns
t_f			143		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 1kV, I_D = 0.5 • I_{D25}		10.6		nC
Q_{gs}			3.3		nC
Q_{gd}			5.5		nC
R_{thJC}				1.1	°C/W
R_{thCS}	TO-247HV		0.21		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			200	mA
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			800	mA
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 200mA, -di/dt = 50A/μs, V_R = 100V		1.6		μs

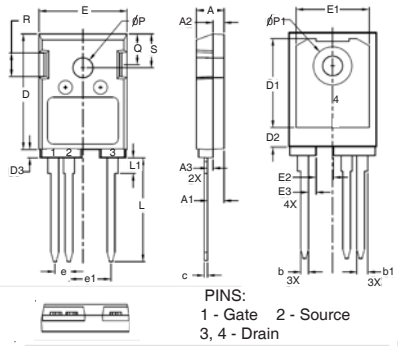
Note: 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

TO-268HV Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETER MIN	MILLIMETER MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.465	.476	11.80	12.10
D2	.295	.307	7.50	7.80
D3	.114	.126	2.90	3.20
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.067	.079	1.70	2.00
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

TO-247HV Outline



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.193	.201	4.90	5.10
A1	.114	.122	2.90	3.10
A2	.075	.083	1.90	2.10
A3	.035	.043	0.90	1.10
b	.053	.059	1.35	1.50
b1	.075	.083	1.90	2.10
c	.022	.030	0.55	0.75
D	.819	.843	20.80	21.40
D1	.638	.646	16.20	16.40
D2	.134	.146	3.40	3.70
D3	.055	.063	1.40	1.60
E	.622	.638	15.80	16.20
E1	.520	.528	13.20	13.40
E2	.118	.126	3.00	3.20
E3	.051	.059	1.30	1.50
e	.100 BSC		2.54 BSC	
e1	.300 BSC		7.62 BSC	
L	.732	.748	18.60	19.00
L1	.106	.118	2.70	3.00
øP	.138	.142	3.50	3.60
øP1	.272	.280	6.90	7.10
Q	.216	.224	5.50	5.70
R	.165	.169	4.20	4.30
S	.240	.248	6.10	6.30

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or moreof the following U.S. patents: 4,835,592 4,860,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ T_J = 25ºC

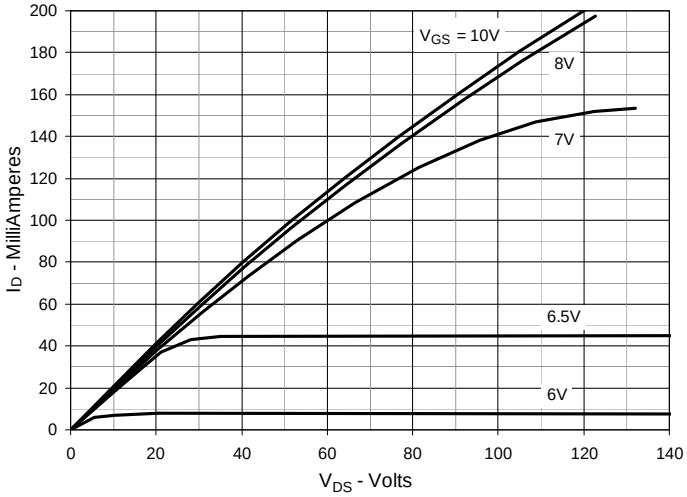


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

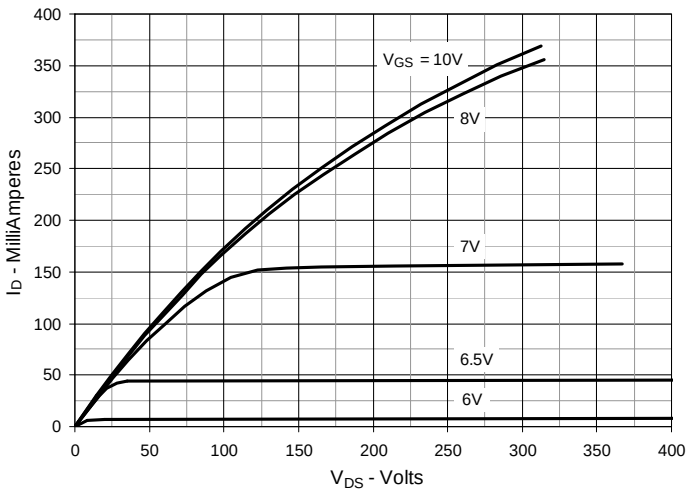


Fig. 3. Output Characteristics @ T_J = 125ºC

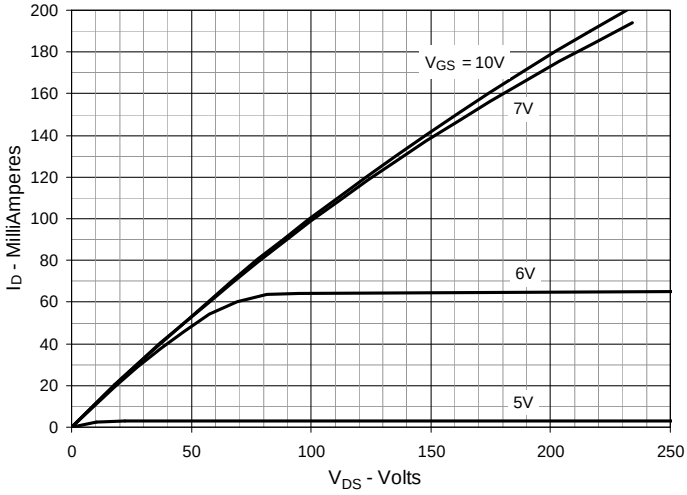


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 100mA Value vs. Junction Temperature

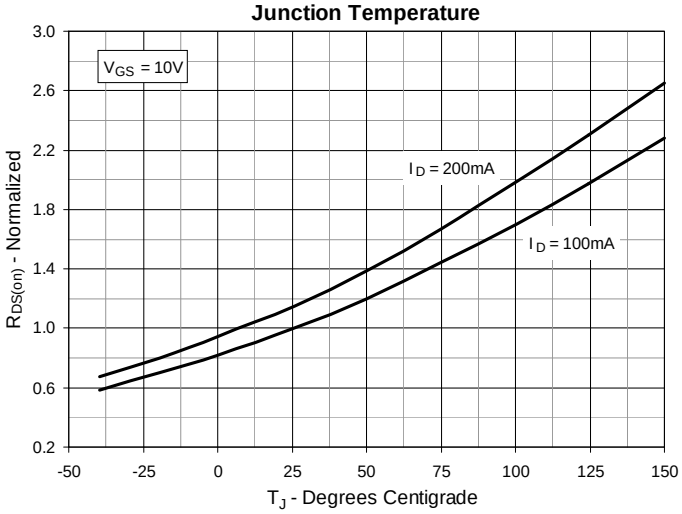


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 100mA Value vs. Drain Current

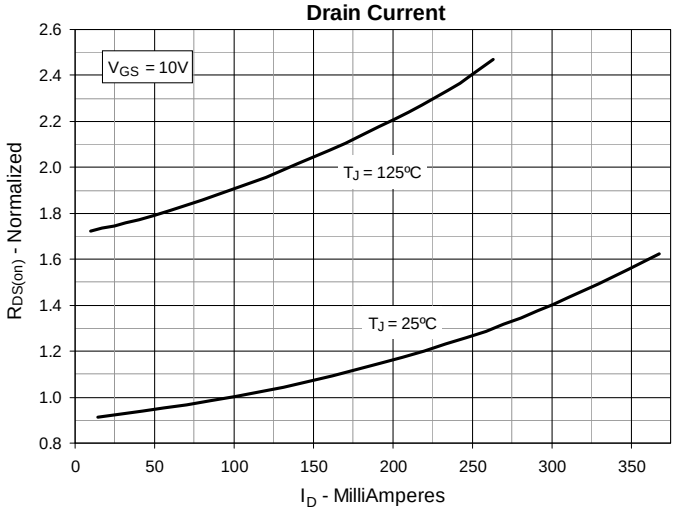
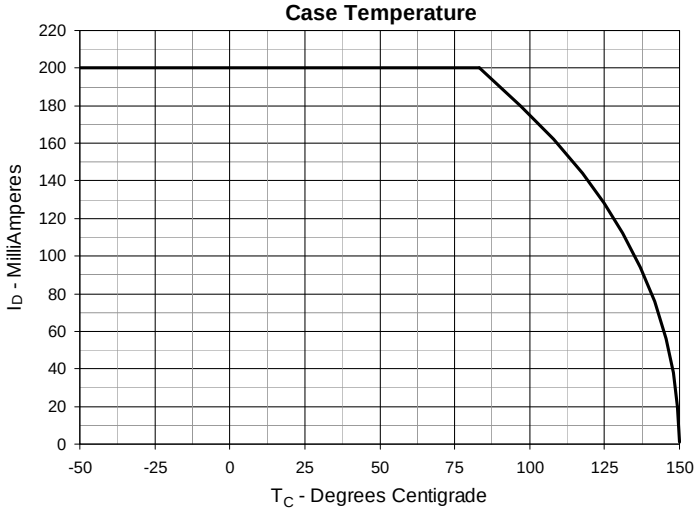


Fig. 6. Maximum Drain Current vs. Case Temperature



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Fig. 7. Input Admittance

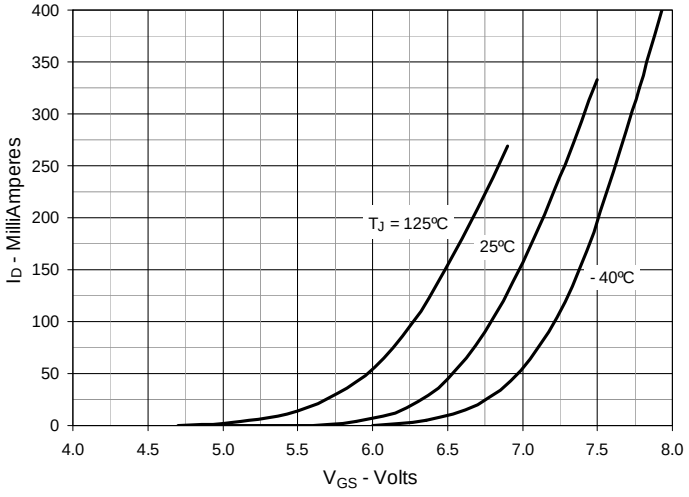


Fig. 8. Transconductance

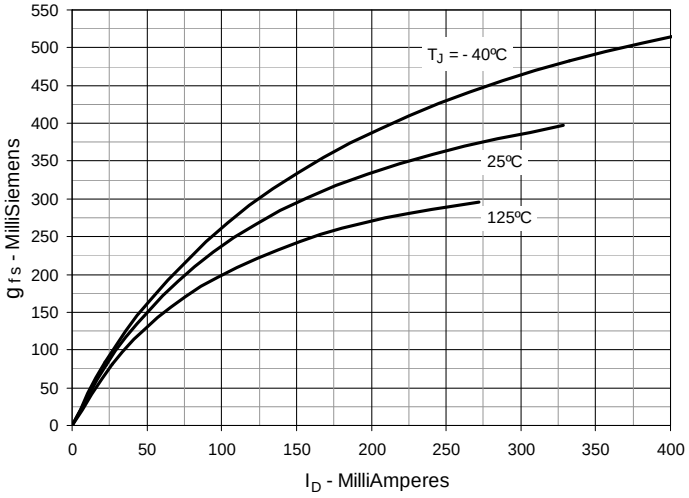


Fig. 9. Forward Voltage Drop of Intrinsic Diode

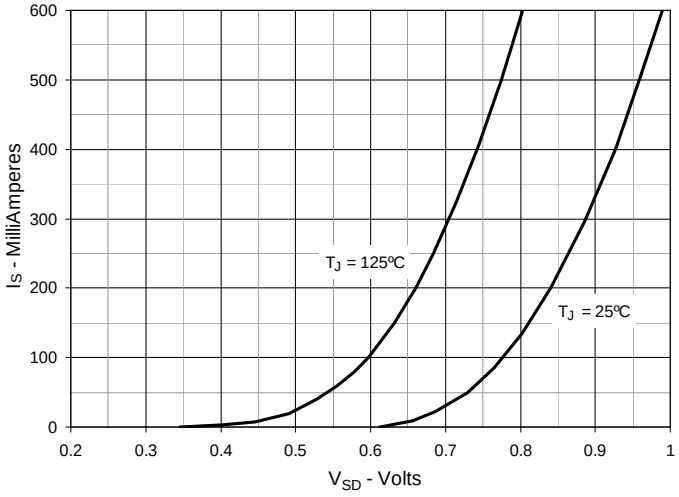


Fig. 10. Gate Charge

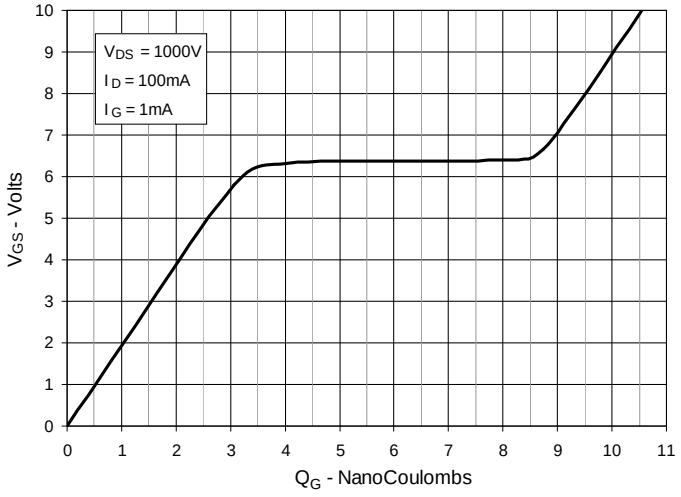


Fig. 11. Capacitance

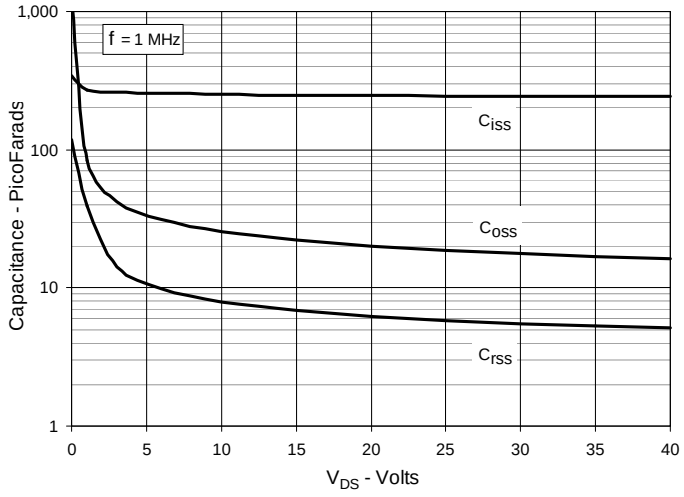
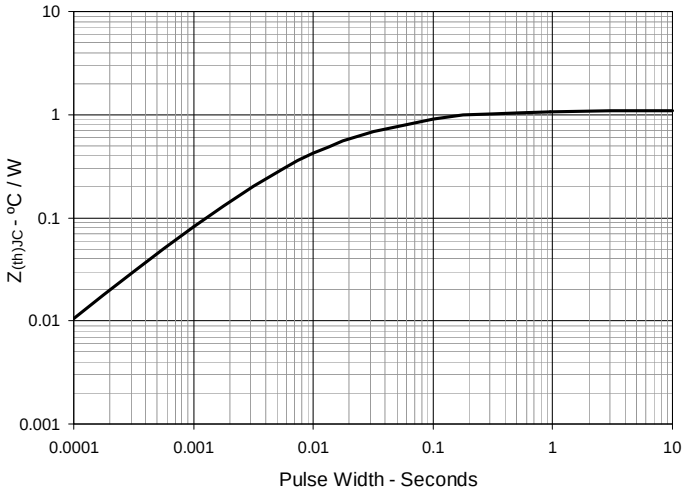


Fig. 12. Maximum Transient Thermal Impedance



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Fig. 13. Forward-Bias Safe Operating Area @ T_C = 25ºC

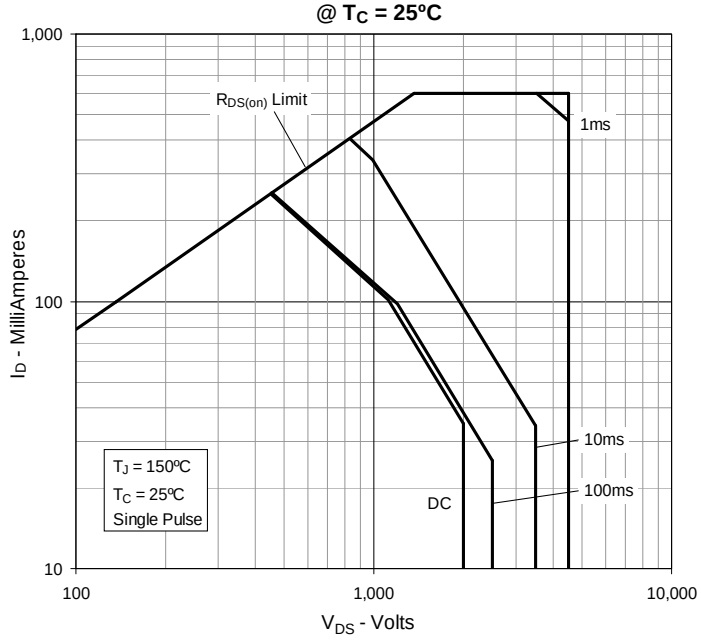
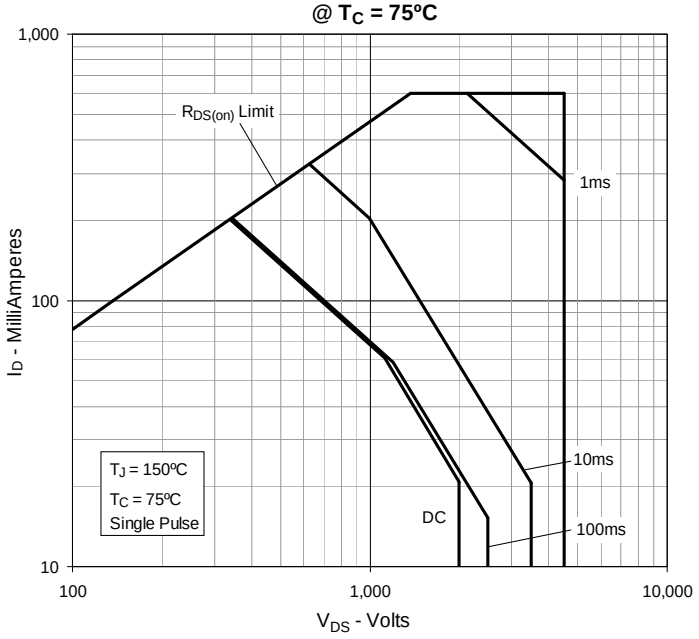


Fig. 14. Forward-Bias Safe Operating Area @ T_C = 75ºC



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